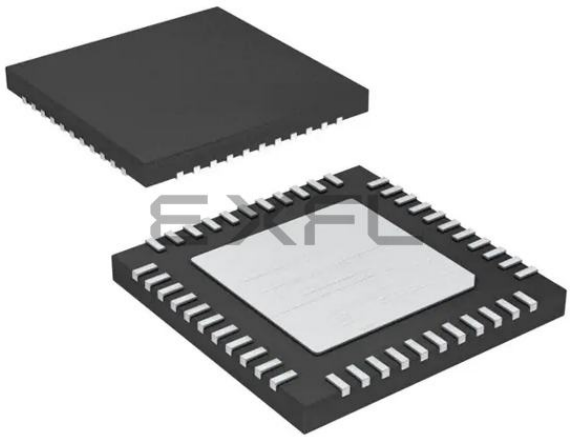
Microchip Technology - DSPIC33FJ128MC204T-I/ML Datasheet



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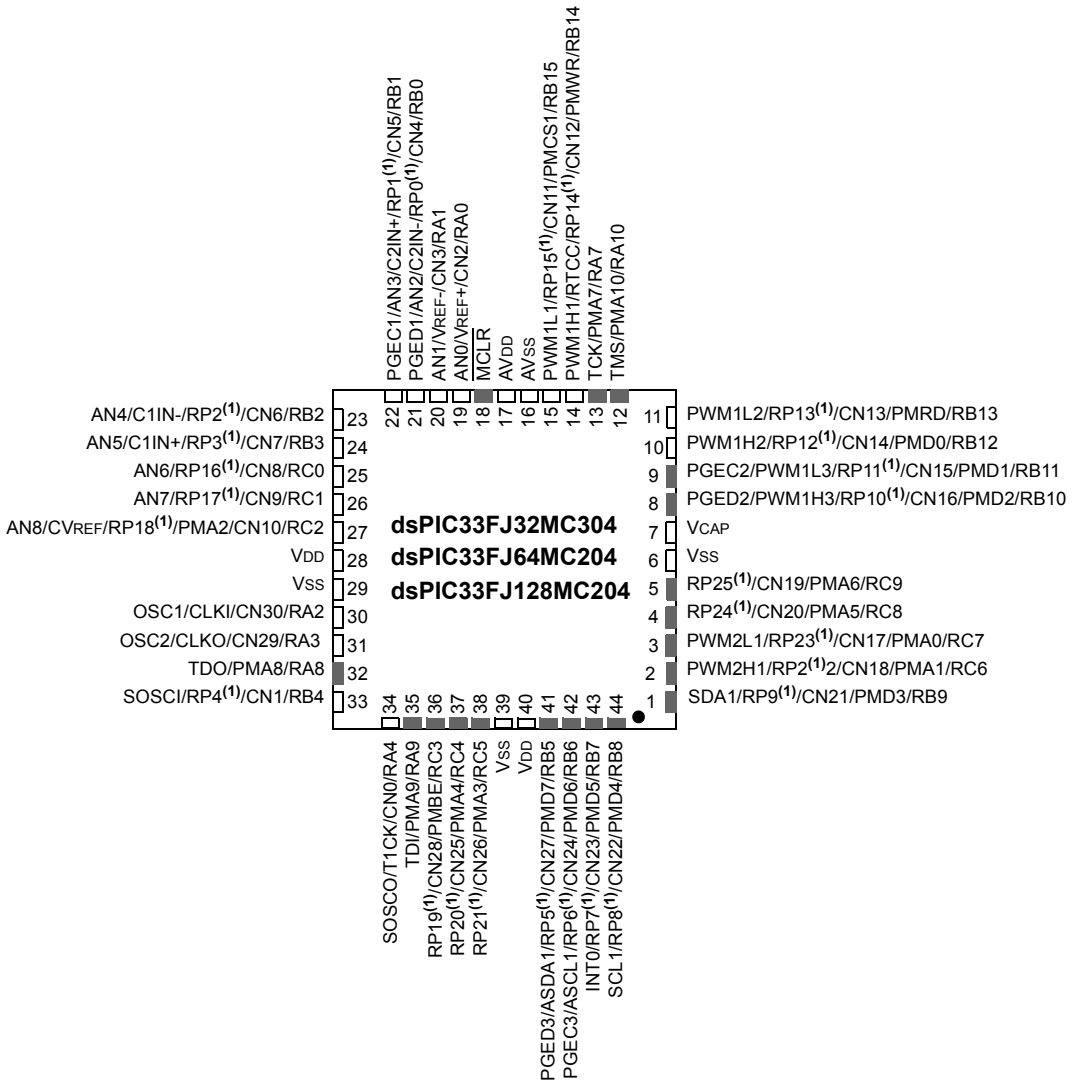
Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	40 MIPs
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, Motor Control PWM, POR, PWM, QEI, WDT
Number of I/O	35
Program Memory Size	128KB (128K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 9x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-VQFN Exposed Pad
Supplier Device Package	44-QFN (8x8)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33fj128mc204t-i-ml

Pin Diagrams (Continued)

44-Pin QFN(2)

■ = Pins are up to 5V tolerant



Note 1: The RPx pins can be used by any remappable peripheral. See Table 1 in this section for the list of available peripherals.

2: The metal plane at the bottom of the device is not connected to any pins and is recommended to be connected to VSS externally.

3.3 DSP Engine Overview

The DSP engine features a high-speed 17-bit by 17-bit multiplier, a 40-bit ALU, two 40-bit saturating accumulators and a 40-bit bidirectional barrel shifter. The barrel shifter is capable of shifting a 40-bit value up to 16 bits right or left, in a single cycle. The DSP instructions operate seamlessly with all other instructions and have been designed for optimal real-time performance. The MAC instruction and other associated instructions can concurrently fetch two data operands from memory while multiplying two W registers and accumulating and optionally saturating the result in the same cycle. This instruction functionality requires that the RAM data space be split for these instructions and linear for all others. Data space partitioning is achieved in a transparent and flexible manner by dedicating certain working registers to each address space.

3.4 Special MCU Features

The dsPIC33FJ32MC302/304, dsPIC33FJ64MCX02/X04 and dsPIC33FJ128MCX02/X04 features a 17-bit by 17-bit single-cycle multiplier that is shared by both the MCU ALU and DSP engine. The multiplier can perform signed, unsigned and mixed-sign multiplication. Using a 17-bit by 17-bit multiplier for 16-bit by 16-bit multiplication not only allows you to perform mixed-sign multiplication, it also achieves accurate results for special operations, such as (-1.0) x (-1.0).

The dsPIC33FJ32MC302/304, dsPIC33FJ64MCX02/X04 and dsPIC33FJ128MCX02/X04 supports 16/16 and 32/16 divide operations, both fractional and integer. All divide instructions are iterative operations. They must be executed within a REPEAT loop, resulting in a total execution time of 19 instruction cycles. The divide operation can be interrupted during any of those 19 cycles without loss of data.

A 40-bit barrel shifter is used to perform up to a 16-bit left or right shift in a single cycle. The barrel shifter can be used by both MCU and DSP instructions.

5.0 FLASH PROGRAM MEMORY

Note 1: This data sheet summarizes the features of the dsPIC33FJ32MC302/304, dsPIC33FJ64MCX02/X04 and dsPIC33FJ128MCX02/X04 family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 5. "Flash Programming"** (DS70191) of the *"dsPIC33F/PIC24H Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The dsPIC33FJ32MC302/304, dsPIC33FJ64MCX02/X04 and dsPIC33FJ128MCX02/X04 devices contain internal Flash program memory for storing and executing application code. The memory is readable, writable and erasable during normal operation over the entire VDD range.

Flash memory can be programmed in two ways:

- In-Circuit Serial Programming™ (ICSP™) programming capability
- Run-Time Self-Programming (RTSP)

ICSP allows a dsPIC33FJ32MC302/304, dsPIC33FJ64MCX02/X04 and dsPIC33FJ128MCX02/X04 device to be serially programmed while in the end application circuit. This is done with two lines for programming clock and programming data (one of the alternate programming pin pairs: PGECx/PGEDx), and three other lines for power (VDD), ground (VSS) and Master Clear (MCLR). This allows customers to manufacture boards with unprogrammed devices and then program the digital signal controller just before shipping the product. This also allows the most recent firmware or a custom firmware to be programmed.

RTSP is accomplished using TBLRD (table read) and TBLWT (table write) instructions. With RTSP, the user application can write program memory data either in blocks or rows of 64 instructions (192 bytes) at a time or a single program memory word, and erase program memory in blocks or pages of 512 instructions (1536 bytes) at a time.

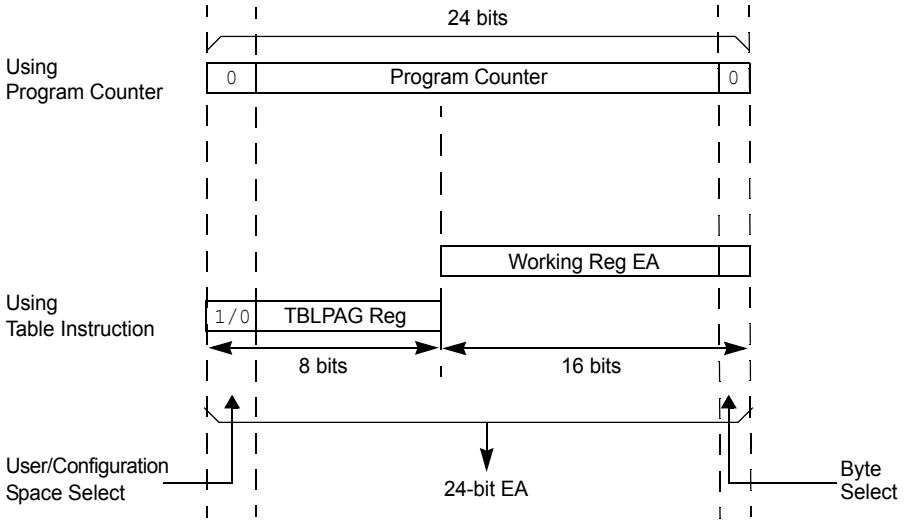
5.1 Table Instructions and Flash Programming

Regardless of the method used, all programming of Flash memory is done with the table read and table write instructions. These allow direct read and write access to the program memory space from the data memory while the device is in normal operating mode. The 24-bit target address in the program memory is formed using bits <7:0> of the TBLPAG register and the Effective Address (EA) from a W register specified in the table instruction, as shown in Figure 5-1.

The TBLRDL and the TBLWTL instructions are used to read or write to bits <15:0> of program memory. The TBLRDL and TBLWTL instructions can access program memory in both Word and Byte modes.

The TBLRDH and TBLWTH instructions are used to read or write to bits <23:16> of program memory. The TBLRDH and TBLWTH can also access program memory in Word or Byte mode.

FIGURE 5-1: ADDRESSING FOR TABLE REGISTERS



REGISTER 7-11: IEC1: INTERRUPT ENABLE CONTROL REGISTER 1 (CONTINUED)

bit 2 **CMIE:** Comparator Interrupt Enable bit
1 = Interrupt request enabled
0 = Interrupt request not enabled

bit 1 **MI2C1IE:** I2C1 Master Events Interrupt Enable bit
1 = Interrupt request enabled
0 = Interrupt request not enabled

bit 0 **SI2C1IE:** I2C1 Slave Events Interrupt Enable bit
1 = Interrupt request enabled
0 = Interrupt request not enabled

REGISTER 10-3: PMD3: PERIPHERAL MODULE DISABLE CONTROL REGISTER 3

U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0
—	—	—	—	—	CMPMD	RTCCMD	PMPMD
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	U-0	U-0	U-0	U-0
CRCMD	DAC1MD	QEI2MD	PWM2MD	—	—	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-11 **Unimplemented:** Read as '0'

bit 10 **CMPMD:** Comparator Module Disable bit
1 = Comparator module is disabled
0 = Comparator module is enabled

bit 9 **RTCCMD:** RTCC Module Disable bit
1 = RTCC module is disabled
0 = RTCC module is enabled

bit 8 **PMPMD:** PMP Module Disable bit
1 = PMP module is disabled
0 = PMP module is enabled

bit 7 **CRCMD:** CRC Module Disable bit
1 = CRC module is disabled
0 = CRC module is enabled

bit 6 **DAC1MD:** DAC1 Module Disable bit
1 = DAC1 module is disabled
0 = DAC1 module is enabled

bit 5 **QEI2MD:** QEI2 Module Disable bit
1 = QEI2 module is disabled
0 = QEI2 module is enabled

bit 4 **PWM2MD:** PWM2 Module Disable bit
1 = PWM2 module is disabled
0 = PWM2 module is enabled

bit 3-0 **Unimplemented:** Read as '0'

REGISTER 11-4: RPINR4: PERIPHERAL PIN SELECT INPUT REGISTER 4

U-0	U-0	U-0	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
—	—	—	T5CKR<4:0>				
bit 15							bit 8

U-0	U-0	U-0	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
—	—	—	T4CKR<4:0>				
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-13 **Unimplemented:** Read as '0'

bit 12-8 **T5CKR<4:0>:** Assign Timer5 External Clock (T5CK) to the corresponding RPn pin
11111 = Input tied to Vss
11001 = Input tied to RP25
•
•
•
00001 = Input tied to RP1
00000 = Input tied to RP0

bit 7-5 **Unimplemented:** Read as '0'

bit 4-0 **T4CKR<4:0>:** Assign Timer4 External Clock (T4CK) to the corresponding RPn pin
11111 = Input tied to Vss
11001 = Input tied to RP25
•
•
•
00001 = Input tied to RP1
00000 = Input tied to RP0

NOTES:

REGISTER 16-8: PxDTCON2: DEAD-TIME CONTROL REGISTER 2(1)

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	DTS3A	DTS3I	DTS2A	DTS2I	DTS1A	DTS1I
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-6 **Unimplemented:** Read as '0'

bit 5 **DTS3A:** Dead-Time Select for PWMxH3 Signal Going Active bit
1 = Dead time provided from Unit B
0 = Dead time provided from Unit A

bit 4 **DTS3I:** Dead-Time Select for PWMxL3 Signal Going Inactive bit
1 = Dead time provided from Unit B
0 = Dead time provided from Unit A

bit 3 **DTS2A:** Dead-Time Select for PWMxH2 Signal Going Active bit
1 = Dead time provided from Unit B
0 = Dead time provided from Unit A

bit 2 **DTS2I:** Dead-Time Select for PWMxL2 Signal Going Inactive bit
1 = Dead time provided from Unit B
0 = Dead time provided from Unit A

bit 1 **DTS1A:** Dead-Time Select for PWMxH1 Signal Going Active bit
1 = Dead time provided from Unit B
0 = Dead time provided from Unit A

bit 0 **DTS1I:** Dead-Time Select for PWMxL1 Signal Going Inactive bit
1 = Dead time provided from Unit B
0 = Dead time provided from Unit A

Note 1: PWM2 supports only one PWM I/O pin pair.

REGISTER 21-19: CiFMSKSEL2: ECAN™ FILTER 15-8 MASK SELECTION REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
F15MSK<1:0>		F14MSK<1:0>		F13MSK<1:0>		F12MSK<1:0>	
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
F11MSK<1:0>		F10MSK<1:0>		F9MSK<1:0>		F8MSK<1:0>	
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-14 **F15MSK<1:0>:** Mask Source for Filter 15 bit
11 = No mask
10 = Acceptance Mask 2 registers contain mask
01 = Acceptance Mask 1 registers contain mask
00 = Acceptance Mask 0 registers contain mask

bit 13-12 **F14MSK<1:0>:** Mask Source for Filter 14 bit (same values as bit 15-14)

bit 11-10 **F13MSK<1:0>:** Mask Source for Filter 13 bit (same values as bit 15-14)

bit 9-8 **F12MSK<1:0>:** Mask Source for Filter 12 bit (same values as bit 15-14)

bit 7-6 **F11MSK<1:0>:** Mask Source for Filter 11 bit (same values as bit 15-14)

bit 5-4 **F10MSK<1:0>:** Mask Source for Filter 10 bit (same values as bit 15-14)

bit 3-2 **F9MSK<1:0>:** Mask Source for Filter 9 bit (same values as bit 15-14)

bit 1-0 **F8MSK<1:0>:** Mask Source for Filter 8 bit (same values as bit 15-14)

REGISTER 22-3: AD1CON3: ADC1 CONTROL REGISTER 3

R/W-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
ADRC	—	—	SAMC<4:0>(1)				
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
ADCS<7:0>(2)							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **ADRC:** ADC Conversion Clock Source bit
1 = ADC internal RC clock
0 = Clock derived from system clock

bit 14-13 **Unimplemented:** Read as '0'

bit 12-8 **SAMC<4:0>:** Auto Sample Time bits(1)
11111 = 31 TAD
•
•
•
00001 = 1 TAD
00000 = 0 TAD

bit 7-0 **ADCS<7:0>:** ADC Conversion Clock Select bits(2)
11111111 = Reserved
•
•
•
•
01000000 = Reserved
00111111 = TCY · (ADCS<7:0> + 1) = 64 · TCY = TAD
•
•
•
00000010 = TCY · (ADCS<7:0> + 1) = 3 · TCY = TAD
00000001 = TCY · (ADCS<7:0> + 1) = 2 · TCY = TAD
00000000 = TCY · (ADCS<7:0> + 1) = 1 · TCY = TAD

Note 1: These bits are only used if AD1CON1<7:5> (SSRC<2:0>) = 111.
2: This bit is not used if AD1CON3<15> (ADRC) = 1.

23.0 AUDIO DIGITAL-TO-ANALOG CONVERTER (DAC)

Note 1: This data sheet summarizes the features of the dsPIC33FJ32MC302/304, dsPIC33FJ64MCX02/X04 and dsPIC33FJ128MCX02/X04 family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 33. "Audio Digital-to-Analog Converter (DAC)"** (DS70211) of the *dsPIC33F/PIC24H Family Reference Manual*, which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The Audio Digital-to-Analog Converter (DAC) module is a 16-bit Delta-Sigma signal converter designed for audio applications. It has two output channels, left and right to support stereo applications. Each DAC output channel provides three voltage outputs, positive DAC output, negative DAC output, and the midpoint voltage output for the dsPIC33FJ64MC804 and dsPIC33FJ128MC804 devices.

23.1 KEY FEATURES

- 16-bit resolution (14-bit accuracy)
- Second-Order Digital Delta-Sigma Modulator
- 256 X Over-Sampling Ratio
- 128-Tap FIR Current-Steering Analog Reconstruction Filter
- 100 KSPS Maximum Sampling Rate
- User controllable Sample Clock
- Input Frequency 45 kHz max
- Differential Analog Outputs
- Signal-To-Noise: 90 dB
- 4-deep input Buffer
- 16-bit Processor I/O, and DMA interfaces

23.2 DAC Module Operation

The functional block diagram of the Audio DAC module is shown in Figure 23-1. The Audio DAC module provides a 4-deep data input FIFO buffer for each output channel. If the DMA module and/or the processor cannot provide output data in a timely manner, and the FIFO becomes empty, the DAC accepts data from the DAC Default Data register (DACDFLT). This safety feature is useful for industrial control applications where the DAC output controls an important processor or machinery. The DACDFLT register should be initialized with a safe output value. Often the safe output value is either the midpoint value (0x8000) or a zero value (0x0000).

The digital interpolator up-samples the input signals, where the over-sampling ratio is 256x which creates data points between the user supplied data points. The interpolator also includes processing by digital filters to provide noise shaping to move the converter noise above 20 kHz (upper limit of the pass band). The output of the interpolator drives the Sigma-Delta modulator. The serial data bit stream from the Sigma-Delta modulator is processed by the reconstruction filter. The differential outputs of the reconstruction filter are amplified by Op Amps to provide the required peak-to-peak voltage swing.

Note: The DAC module is designed specifically for audio applications and is not recommended for control type applications.

23.3 DAC Output Format

The DAC output data stream can be in a two's complement signed number format or as an unsigned number format.

The Audio DAC module features the ability to accept the 16-bit input data in a two's complement signed number format or as an unsigned number format. The data formatting is controlled by the Data Format Control bit (FORM<8>) in the DAC1CON register. The supported formats are:

- 1 = Signed (two's complement)
- 0 = Unsigned

If the FORM bit is configured for Unsigned data the user input data yields the following behavior:

- 0xFFFF = most positive output voltage
- 0x8000 = mid point output voltage
- 0x7FFF = a value just below the midpoint
- 0x0000 = minimum output voltage

If the FORM bit is configured for signed data the user input data yields the following behavior:

- 0x7FFF = most positive output voltage
- 0x0000 = mid point output voltage
- 0xFFFF = value just below the midpoint
- 0x8000 = minimum output voltage

The Audio DAC provides an analog output proportional to the digital input value. The maximum 100,000 samples per second (100 ksps) update rate provides good quality audio reproduction.

REGISTER 24-1: CMCON: COMPARATOR CONTROL REGISTER (CONTINUED)

bit 6 **C1OUT:** Comparator 1 Output bit
When C1INV = 0:
1 = C1 VIN+ > C1 VIN-
0 = C1 VIN+ < C1 VIN-
When C1INV = 1:
0 = C1 VIN+ > C1 VIN-
1 = C1 VIN+ < C1 VIN-

bit 5 **C2INV:** Comparator 2 Output Inversion bit
1 = C2 output inverted
0 = C2 output not inverted

bit 4 **C1INV:** Comparator 1 Output Inversion bit
1 = C1 output inverted
0 = C1 output not inverted

bit 3 **C2NEG:** Comparator 2 Negative Input Configure bit
1 = Input is connected to VIN+
0 = Input is connected to VIN-
See Figure 24-1 for Comparator modes.

bit 2 **C2POS:** Comparator 2 Positive Input Configure bit
1 = Input is connected to VIN+
0 = Input is connected to CVREF
See Figure 24-1 for Comparator modes.

bit 1 **C1NEG:** Comparator 1 Negative Input Configure bit
1 = Input is connected to VIN+
0 = Input is connected to VIN-
See Figure 24-1 for Comparator modes.

bit 0 **C1POS:** Comparator 1 Positive Input Configure bit
1 = Input is connected to VIN+
0 = Input is connected to CVREF
See Figure 24-1 for Comparator modes.

Note 1: If C2OUTEN = 1, the C2OUT peripheral output must be configured to an available RPx pin. See **Section 11.6 "Peripheral Pin Select"** for more information.

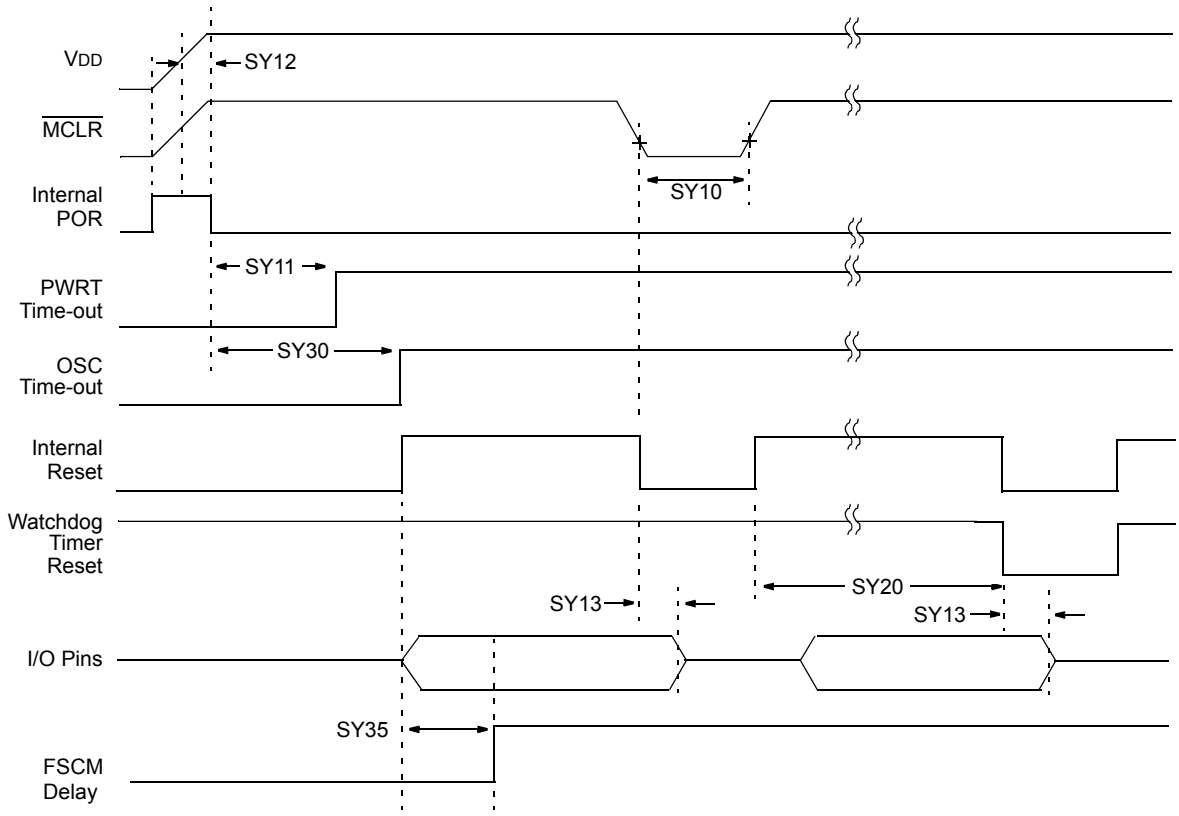
2: If C1OUTEN = 1, the C1OUT peripheral output must be configured to an available RPx pin. See **Section 11.6 "Peripheral Pin Select"** for more information.

TABLE 28-2: dsPIC33F CONFIGURATION BITS DESCRIPTION

Bit Field	Register	RTSP Effect	Description
BWRP	FBS	Immediate	Boot Segment Program Flash Write Protection 1 = Boot segment can be written 0 = Boot segment is write-protected
BSS<2:0>	FBS	Immediately	Boot Segment Program Flash Code Protection Size X11 = No Boot program Flash segment Boot space is 1K Instruction Words (except interrupt vectors) 110 = Standard security; boot program Flash segment ends at 0x0007FE 010 = High security; boot program Flash segment ends at 0x0007FE Boot space is 4K Instruction Words (except interrupt vectors) 101 = Standard security; boot program Flash segment, ends at 0x001FFE 001 = High security; boot program Flash segment ends at 0x001FFE Boot space is 8K Instruction Words (except interrupt vectors) 100 = Standard security; boot program Flash segment ends at 0x003FFE 000 = High security; boot program Flash segment ends at 0x003FFE
RBS<1:0>(1)	FBS	Immediate	Boot Segment RAM Code Protection Size 11 = No Boot RAM defined 10 = Boot RAM is 128 bytes 01 = Boot RAM is 256 bytes 00 = Boot RAM is 1024 bytes
SWRP(1)	FSS(1)	Immediate	Secure Segment Program Flash Write-Protect bit 1 = Secure Segment can bet written 0 = Secure Segment is write-protected
SSS<2:0>	FSS	Immediate	Secure Segment Program Flash Code Protection Size **(Secure segment is not implemented on 32K devices)** X11 = No Secure program flash segment Secure space is 4K IW less BS 110 = Standard security; secure program Flash segment starts at End of BS, ends at 0x001FFE 010 = High security; secure program Flash segment starts at End of BS, ends at 0x001FFE Secure space is 8K IW less BS 101 = Standard security; secure program Flash segment starts at End of BS, ends at 0x003FFE 001 = High security; secure program Flash segment starts at End of BS, ends at 0x003FFE Secure space is 16K IW less BS 100 = Standard security; secure program Flash segment starts at End of BS, ends at 007FFEh 000 = High security; secure program Flash segment starts at End of BS, ends at 0x007FFE
RSS<1:0>(1)	FSS(1)	Immediate	Secure Segment RAM Code Protection 11 = No Secure RAM defined 10 = Secure RAM is 256 Bytes less BS RAM 01 = Secure RAM is 2048 Bytes less BS RAM 00 = Secure RAM is 4096 Bytes less BS RAM

Note 1: This Configuration register is not available on dsPIC33FJ32MC302/304 devices.

FIGURE 31-4: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER AND POWER-UP TIMER TIMING CHARACTERISTICS



Note: Refer to Figure 31-1 for load conditions.

FIGURE 31-13: QEI MODULE INDEX PULSE TIMING CHARACTERISTICS

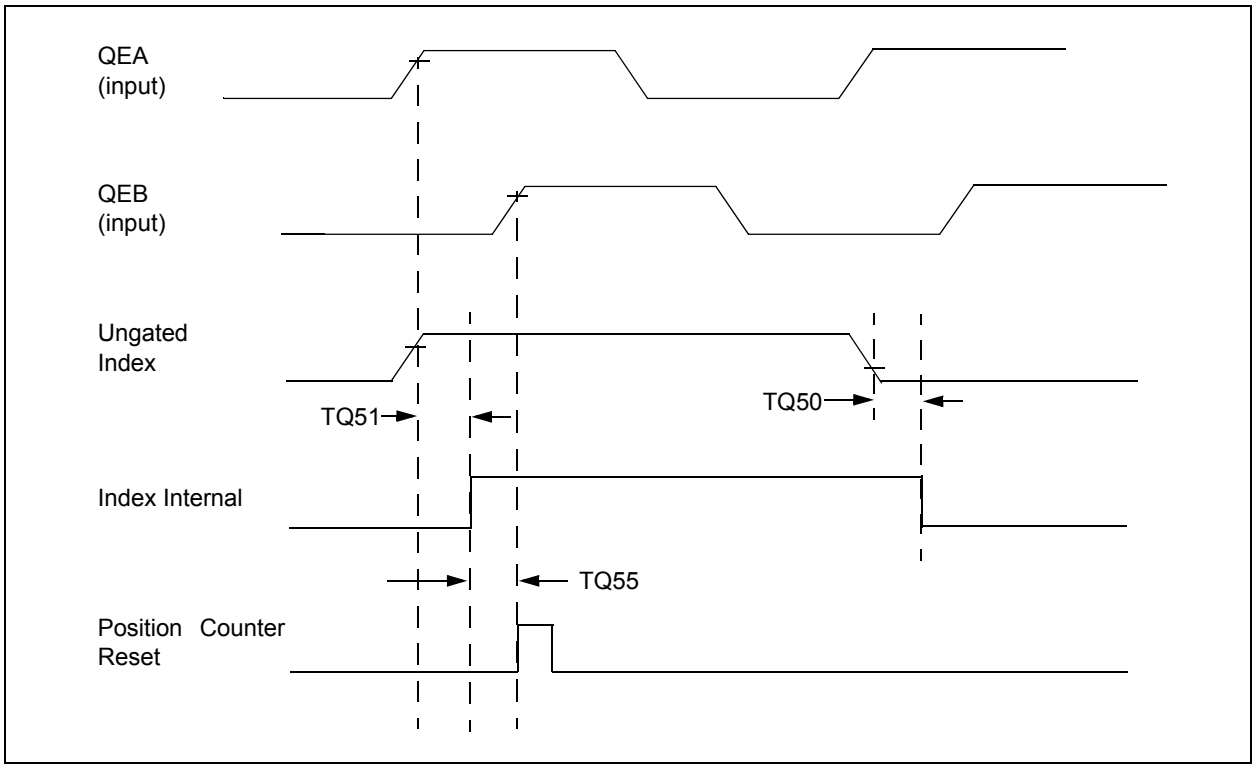


TABLE 31-31: QEI INDEX PULSE TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended			
Param No.	**Symbol**	**Characteristic(1)**	**Min**	**Max**	**Units**	**Conditions**
TQ50	TqIL	Filter Time to Recognize Low, with Digital Filter	3 * N * TCY	—	ns	N = 1, 2, 4, 16, 32, 64, 128 and 256 **(Note 2)**
TQ51	TqiH	Filter Time to Recognize High, with Digital Filter	3 * N * TCY	—	ns	N = 1, 2, 4, 16, 32, 64, 128 and 256 **(Note 2)**
TQ55	Tqidxr	Index Pulse Recognized to Position Counter Reset (ungated index)	3 TCY	—	ns	—

Note 1: These parameters are characterized but not tested in manufacturing.

2: Alignment of index pulses to QEA and QEB is shown for position counter Reset timing only. Shown for forward direction only (QEA leads QEB). Same timing applies for reverse direction (QEA lags QEB) but index pulse recognition occurs on falling edge.

TABLE 31-38: SPIx SLAVE MODE (FULL-DUPLEX, CKE = 0, CKP = 1, SMP = 0) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤TA ≤+85°C for Industrial -40°C ≤TA ≤+125°C for Extended				
Param No.	**Symbol**	**Characteristic(1)**	**Min**	**Typ(2)**	**Max**	**Units**	**Conditions**
SP70	TscP	Maximum SCK Input Frequency	—	—	15	MHz	See **Note 3**
SP72	TscF	SCKx Input Fall Time	—	—	—	ns	See parameter DO32 and **Note 4**
SP73	TscR	SCKx Input Rise Time	—	—	—	ns	See parameter DO31 and **Note 4**
SP30	TdoF	SDOx Data Output Fall Time	—	—	—	ns	See parameter DO32 and **Note 4**
SP31	TdoR	SDOx Data Output Rise Time	—	—	—	ns	See parameter DO31 and **Note 4**
SP35	TscH2doV, TscL2doV	SDOx Data Output Valid after SCKx Edge	—	6	20	ns	—
SP36	TdoV2scH, TdoV2scL	SDOx Data Output Setup to First SCKx Edge	30	—	—	ns	—
SP40	TdiV2scH, TdiV2scL	Setup Time of SDIx Data Input to SCKx Edge	30	—	—	ns	—
SP41	TscH2diL, TscL2diL	Hold Time of SDIx Data Input to SCKx Edge	30	—	—	ns	—
SP50	TssL2scH, TssL2scL	$\overline{SSx}$ ↓to SCKx ↑ or SCKx Input	120	—	—	ns	—
SP51	TssH2doZ	$\overline{SSx}$ ↑ to SDOx Output High-Impedance(4)	10	—	50	ns	—
SP52	TscH2ssH TscL2ssH	$\overline{SSx}$ after SCKx Edge	1.5 TCY + 40	—	—	ns	See **Note 4**

Note 1: These parameters are characterized, but are not tested in manufacturing.

2: Data in "Typ" column is at 3.3V, 25°C unless otherwise stated.

3: The minimum clock period for SCKx is 66.7 ns. Therefore, the SCK clock generated by the Master must not violate this specification.

4: Assumes 50 pF load on all SPIx pins.

TABLE 32-16: ADC MODULE SPECIFICATIONS (10-BIT MODE)

AC CHARACTERISTICS		Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤TA ≤+150°C for High Temperature					
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ**	**Max**	**Units**	**Conditions**
ADC Accuracy (10-bit Mode) – Measurements with External VREF+/VREF-(1)							
HAD20b	Nr	Resolution(3)	10 data bits			bits	—
HAD21b	INL	Integral Nonlinearity	-3	—	3	LSb	VINL = AVSS = VREFL = 0V, AVDD = VREFH = 3.6V
HAD22b	DNL	Differential Nonlinearity	> -1	—	< 1	LSb	VINL = AVSS = VREFL = 0V, AVDD = VREFH = 3.6V
HAD23b	GERR	Gain Error	-5	—	6	LSb	VINL = AVSS = VREFL = 0V, AVDD = VREFH = 3.6V
HAD24b	EOFF	Offset Error	-1	—	5	LSb	VINL = AVSS = VREFL = 0V, AVDD = VREFH = 3.6V
ADC Accuracy (10-bit Mode) – Measurements with Internal VREF+/VREF-(1)							
HAD20b	Nr	Resolution(3)	10 data bits			bits	—
HAD21b	INL	Integral Nonlinearity	-2	—	2	LSb	VINL = AVSS = 0V, AVDD = 3.6V
HAD22b	DNL	Differential Nonlinearity	> -1	—	< 1	LSb	VINL = AVSS = 0V, AVDD = 3.6V
HAD23b	GERR	Gain Error	-5	—	15	LSb	VINL = AVSS = 0V, AVDD = 3.6V
HAD24b	EOFF	Offset Error	-1.5	—	7	LSb	VINL = AVSS = 0V, AVDD = 3.6V
Dynamic Performance (10-bit Mode)(2)							
HAD33b	FNYQ	Input Signal Bandwidth	—	—	400	kHz	—

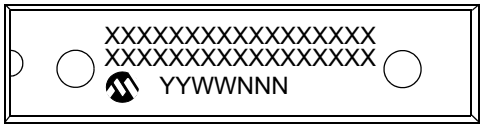
Note 1: These parameters are characterized, but are tested at 20 ksps only.

2: These parameters are characterized by similarity, but are not tested in manufacturing.

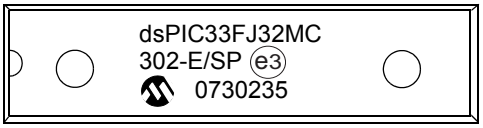
3: Injection currents > | 0 | can affect the ADC results by approximately 4-6 counts.

33.0 PACKAGING INFORMATION

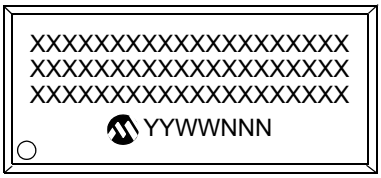
28-Lead SPDIP



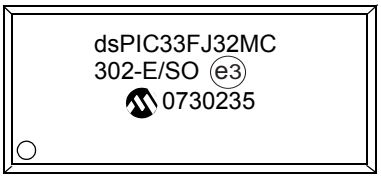
Example



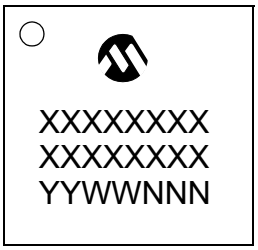
28-Lead SOIC (.300”)



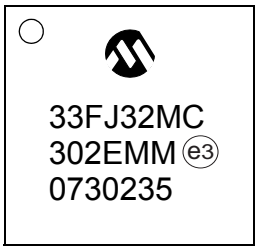
Example



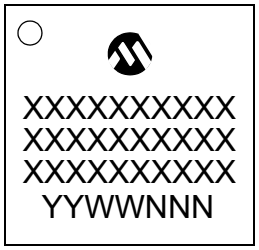
28-Lead QFN-S



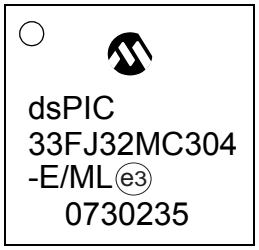
Example



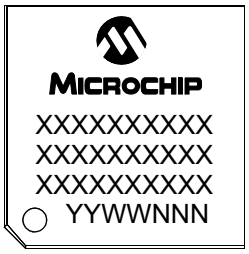
44-Lead QFN



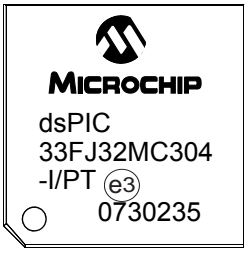
Example



44-Lead TQFP



Example

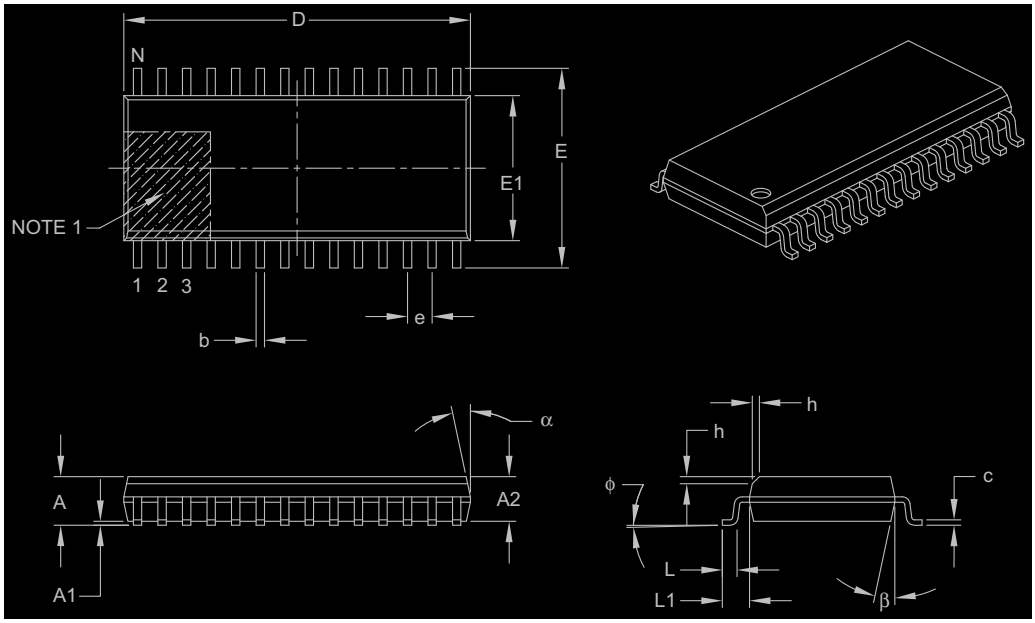


Legend:	XX...X	Customer-specific information
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week ‘01’)
	NNN	Alphanumeric traceability code
	e3	Pb-free JEDEC designator for Matte Tin (Sn)
	*	This package is Pb-free. The Pb-free JEDEC designator (e3) can be found on the outer packaging for this package.

Note: If the full Microchip part number cannot be marked on one line, it is carried over to the next line, thus limiting the number of available characters for customer-specific information.

28-Lead Plastic Small Outline (SO) – Wide, 7.50 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		28	
Pitch	e		1.27 BSC	
Overall Height	A	–	–	2.65
Molded Package Thickness	A2	2.05	–	–
Standoff §	A1	0.10	–	0.30
Overall Width	E		10.30 BSC	
Molded Package Width	E1		7.50 BSC	
Overall Length	D		17.90 BSC	
Chamfer (optional)	h	0.25	–	0.75
Foot Length	L	0.40	–	1.27
Footprint	L1		1.40 REF	
Foot Angle Top	ϕ	0°	–	8°
Lead Thickness	c	0.18	–	0.33
Lead Width	b	0.31	–	0.51
Mold Draft Angle Top	α	5°	–	15°
Mold Draft Angle Bottom	β	5°	–	15°

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic.
3. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.15 mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.
REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-052B

Revision F (August 2011)

This revision includes typographical and formatting changes throughout the data sheet text.

All other major changes are referenced by their respective section in the following table.

TABLE A-5: MAJOR SECTION UPDATES

Section Name	Update Description
Section 28.0 "Special Features"	Added Note 3 to the Connections for the On-chip Voltage Regulator diagram (see Figure 28-1).
Section 31.0 "Electrical Characteristics"	Removed Voltage on VCAP with respect to Vss from the Absolute Maximum Ratings. Removed Note 3 and parameter DC10 (VCORE) from the DC Temperature and Voltage Specifications (see Table 31-4). Updated the Characteristics definition and Conditions for parameter BO10 in the Electrical Characteristics: BOR (see Table 31-11). Added Note 1 to the Internal Voltage Regulator Specifications (see Table 31-13).

Revision G (April 2012)

This revision includes typographical and formatting changes throughout the data sheet text.

In addition, where applicable, new sections were added to each peripheral chapter that provide information and links to related resources, as well as helpful tips. For examples, see **Section 9.2 "Oscillator Resources"** and **Section 22.4 "ADC Helpful Tips"**.

All other major changes are referenced by their respective section in the following table.

TABLE A-6: MAJOR SECTION UPDATES

Section Name	Update Description
Section 2.0 "Guidelines for Getting Started with 16-bit Digital Signal Controllers"	Added two new tables: • Crystal Recommendations (see Table 2-1) • Resonator Recommendations (see Table 2-2)
Section 31.0 "Electrical Characteristics"	Updated parameters DO10 and DO20 and removed parameters DO16 and DO26 in the DC Characteristics: I/O Pin Output Specifications (see Table 31-10)